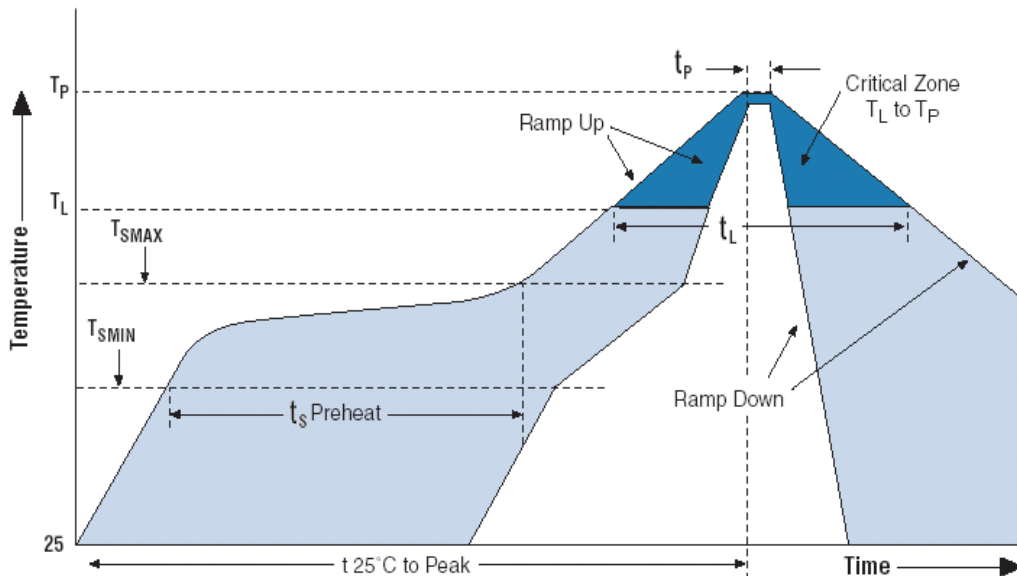


Soldering Reflow for XHFC-1SU / XHFC-2SU


Profile Feature	Sn-Pb eutectic assembly	Pb-free assembly
Average ramp-up rate (T_L to T_p)	3°C/second max.	3°C/second max.
Preheat <ul style="list-style-type: none"> - Temperature Min (T_{SMIN}) - Temperature Max (T_{SMAX}) - Time (min to max) (t_s) 	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
T_{SMAX} to T_L – Ramp-up Rate		3°C/second max
Time maintained above: <ul style="list-style-type: none"> - Temperature (T_L) - Time (t_L) 	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature (T_p)	240 +0/-5°C	260 +0/-5°C
Time within 5°C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



The recommended profiles for soldering reflow of XHFC-1SU / XHFC-2SU for **Sn-Pb eutectic** as well as **Pb-free assembly** mainly correspond to the commonly applied JEDEC Standard **JSTD-020C**. But to ensure best surface mounting quality, it is encouraged to use the provisions of **Pb-free assembly**. The table and graph above illustrate the respective soldering reflow.

Caution: Vacuum bags contain moisture sensitive devices!

Surface mount products may have a crack when thermal stress is applied during surface mount assembly if they have absorbed atmospheric moisture. It is recommended that these products are handled under specific conditions described as follows:

Package Type	Storage Condition after unpacking (as maximum)	Rebake Condition as minimum
 LQFP 64	Within 168 hours (30°C/60% RH) MSL 3	125°C 24 hours



tel.: +49-221-9124 0
 fax: +49-221-9124 100
 web: www.CologneChip.com
 e-Mail: info@CologneChip.com